

## MSDS LIST FOR NA PRODUCT

Model : FV-08WQ1/FV-GKF32S1

ITEM	USED AT	FUNCTION	COMPONENT	RATIO
Miss mold F1 (PFOA free)	MOlding Process	Release agent	Fluorine compound	<1 (wt%)
			Isohexane 2-Methylpentane	10~20 (wt%)
			Isohexane 3-Methylpentane	10~20 (wt%)
			N-hexane	<1 (wt%)
			Propane	10~20 (wt%)
			Butane	50~60 (wt%)
Bren call	MOlding Process	Exterior cleaning (products)	Ethanol	85.5 (%)
			Isopropyl alcohol	4.9 (%)
			1-propanol	9.6 (%)
			Moisture	0.2以下 (%)
GP Cleaner	MOlding Process	Exterior cleaning (products)	N-heptane	70~80 (%)
			Propane	20~30 (%)
NTX Eco thinner	MOlding Process	Mold cleaner	The combined organic compound (Including alcohol,containing hydrocarbons)	
Sumi mold card	MOlding Process	Mold rust inhibitor	Rust inhibitor	1~5 (wt%)
			Cyclohexane	30~40 (wt%)
			Dimethyl ether	60~70 (wt%)
			Kerosene	1~5 (wt%)
			Mineral oil	1~5 (wt%)
Tomi clean S Series	MOlding Process	Molding machine cylinder internal cleaning agent	Olefin resin modified product	More than 70%
			Other additives	Less than 30%